

# NTZD3156C

## Small Signal MOSFET

20 V, 540 mA / -20 V, -430 mA  
Complementary N- and P-Channel  
MOSFETs with Integrated Pull Up/Down  
Resistor and ESD Protection



ON Semiconductor®

<http://onsemi.com>

### Features

- Leading Trench Technology for Low  $R_{DS(on)}$  Performance
- High Efficiency System Performance
- Low Threshold Voltage
- Integrated G-S Resistor on Both Devices
- ESD Protected Gate
- Small Footprint 1.6 x 1.6 mm
- These are Pb-Free Devices

### Applications

- Load/Power Switching with Level Shift
- Portable Electronic Products such as GPS, Cell Phones, DSC, PMP, Bluetooth Accessories

### MAXIMUM RATINGS ( $T_J = 25^\circ\text{C}$ unless otherwise specified)

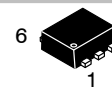
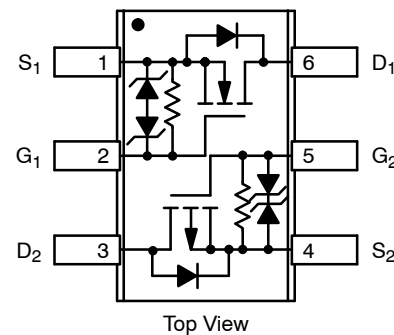
Parameter		Symbol	Value	Unit	
Drain-to-Source Voltage		$V_{DSS}$	20	V	
Gate-to-Source Voltage		$V_{GS}$	$\pm 6$	V	
N-Channel Continuous Drain Current (Note 1)	Steady State	$T_A = 25^\circ\text{C}$	540	mA	
			$T_A = 85^\circ\text{C}$		390
	$t \leq 5$ s	$T_A = 25^\circ\text{C}$	570		
			$T_A = 85^\circ\text{C}$		-430
P-Channel Continuous Drain Current (Note 1)	Steady State	$T_A = 25^\circ\text{C}$	-310	mA	
			$T_A = 85^\circ\text{C}$		-455
	$t \leq 5$ s	$T_A = 25^\circ\text{C}$	-455		
			$T_A = 85^\circ\text{C}$		-455
Power Dissipation (Note 1)	Steady State	$T_A = 25^\circ\text{C}$	$P_D$	250	mW
			$t \leq 5$ s	280	
Pulsed Drain Current	N-Channel	$t_p = 10 \mu\text{s}$	$I_{DM}$	1500	mA
	P-Channel			-750	
Operating Junction and Storage Temperature		$T_J, T_{STG}$	-55 to 150	$^\circ\text{C}$	
Source Current (Body Diode)		$I_S$	350	mA	
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)		$T_L$	260	$^\circ\text{C}$	

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. Surface-mounted on FR4 board using 1 in sq. pad size (Cu area = 1.127 in sq [1 oz] including traces).

$V_{(BR)DSS}$	$R_{DS(on)}$ Max	$I_D$ Max (Note 1)
N-Channel 20 V	0.55 $\Omega$ @ 4.5 V	540 mA
	0.7 $\Omega$ @ 2.5 V	
	0.9 $\Omega$ @ 1.8 V	
P-Channel -20 V	0.9 $\Omega$ @ -4.5 V	-430 mA
	1.2 $\Omega$ @ -2.5 V	
	2.0 $\Omega$ @ -1.8 V	

### PINOUT: SOT-563



SOT-563-6  
CASE 463A  
STYLE 9

### MARKING DIAGRAM



ZC = Specific Device Code  
M = Date Code  
▪ = Pb-Free Package

(Note: Microdot may be in either location)

### ORDERING INFORMATION

Device	Package	Shipping†
NTZD3156CT1G	SOT-563	4000 / Tape & Reel
NTZD3156CT2G	SOT-563	4000 / Tape & Reel
NTZD3156CT5G	SOT-563	8000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

# NTZD3156C

## Thermal Resistance Ratings

Parameter	Symbol	Max	Unit
Junction-to-Ambient – Steady State (Note 2)	$R_{\theta JA}$	116	°C/W
Junction-to-Ambient – $t = 5$ s (Note 2)		304	

2. Surface mounted on FR4 board using 1 in sq pad size (Cu area = 1.127 in sq [1 oz] including traces).

## ELECTRICAL CHARACTERISTICS ( $T_J = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	N/P	Test Condition	Min	Typ	Max	Unit
<b>OFF CHARACTERISTICS</b>							
Drain-to-Source Breakdown Voltage	$V_{(BR)DSS}$	N	$V_{GS} = 0\text{ V}$	$I_D = 250\ \mu\text{A}$	20		V
		P		$I_D = -250\ \mu\text{A}$	-20		
Drain-to-Source Breakdown Voltage Temperature Coefficient	$V_{(BR)DSS}/T_J$				20		mV/°C
Zero Gate Voltage Drain Current	$I_{DSS}$	N	$V_{GS} = 0\text{ V}, V_{DS} = 16\text{ V}$	$T_J = 25^\circ\text{C}$		1.0	$\mu\text{A}$
		P	$V_{GS} = 0\text{ V}, V_{DS} = -16\text{ V}$			-1.0	
		N	$V_{GS} = 0\text{ V}, V_{DS} = 16\text{ V}$	$T_J = 125^\circ\text{C}$		2.0	$\mu\text{A}$
		P	$V_{GS} = 0\text{ V}, V_{DS} = -16\text{ V}$			-5.0	
Gate-to-Source Leakage Current	$I_{GSS}$	N	$V_{DS} = 0\text{ V}, V_{GS} = \pm 4.5\text{ V}$			$\pm 50$	$\mu\text{A}$
		P				$\pm 50$	

## ON CHARACTERISTICS (Note 3)

Gate Threshold Voltage	$V_{GS(TH)}$	N	$V_{GS} = V_{DS}$	$I_D = 250\ \mu\text{A}$	0.45	1.0	V
		P		$I_D = -250\ \mu\text{A}$	-0.45	-1.0	
Gate Threshold Temperature Coefficient	$V_{GS(TH)}/T_J$				2.0		-mV/°C
Drain-to-Source On Resistance	$R_{DS(on)}$	N	$V_{GS} = 4.5\text{ V}, I_D = 540\text{ mA}$		0.19	0.55	$\Omega$
		P	$V_{GS} = -4.5\text{ V}, I_D = -430\text{ mA}$		0.39	0.9	
		N	$V_{GS} = 2.5\text{ V}, I_D = 500\text{ mA}$		0.26	0.7	
		P	$V_{GS} = -2.5\text{ V}, I_D = -300\text{ mA}$		0.53	1.2	
		N	$V_{GS} = 1.8\text{ V}, I_D = 350\text{ mA}$		0.36	0.9	
		P	$V_{GS} = -1.8\text{ V}, I_D = -150\text{ mA}$		0.72	2.0	
Forward Transconductance	$g_{FS}$	N	$V_{DS} = 10\text{ V}, I_D = 540\text{ mA}$		1.46		S
		P	$V_{DS} = -10\text{ V}, I_D = -430\text{ mA}$		1.18		

## CHARGES, CAPACITANCES AND GATE RESISTANCE

Input Capacitance	$C_{ISS}$	N	$f = 1\text{ MHz}, V_{GS} = 0\text{ V}$ $V_{DS} = 16\text{ V}$		72		pF
Output Capacitance	$C_{OSS}$				13		
Reverse Transfer Capacitance	$C_{RSS}$				10		
Input Capacitance	$C_{ISS}$	P	$f = 1\text{ MHz}, V_{GS} = 0\text{ V}$ $V_{DS} = -16\text{ V}$		93		
Output Capacitance	$C_{OSS}$				15		
Reverse Transfer Capacitance	$C_{RSS}$				11		

3. Pulse Test: pulse width  $\leq 300\ \mu\text{s}$ , duty cycle  $\leq 2\%$

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## ELECTRICAL CHARACTERISTICS ( $T_J = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	N/P	Test Condition	Min	Typ	Max	Unit
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### CHARGES, CAPACITANCES AND GATE RESISTANCE

Total Gate Charge	$Q_{G(TOT)}$	N	$V_{GS} = 4.5\text{ V}, V_{DS} = 10\text{ V}; I_D = 540\text{ mA}$		1.39	2.5	nC
Threshold Gate Charge	$Q_{G(TH)}$				0.1		
Gate-to-Source Charge	$Q_{GS}$				0.26		
Gate-to-Drain Charge	$Q_{GD}$				0.39		
Total Gate Charge	$Q_{G(TOT)}$	P	$V_{GS} = -4.5\text{ V}, V_{DS} = -10\text{ V}; I_D = -430\text{ mA}$		1.49	2.5	
Threshold Gate Charge	$Q_{G(TH)}$				0.1		
Gate-to-Source Charge	$Q_{GS}$				0.3		
Gate-to-Drain Charge	$Q_{GD}$				0.37		

### SWITCHING CHARACTERISTICS ( $V_{GS} = V$ ) (Note 4)

Turn-On Delay Time	$t_{d(ON)}$	N	$V_{GS} = 4.5\text{ V}, V_{DD} = 10\text{ V}, I_D = 540\text{ mA},$ $R_G = 10\ \Omega$		7.7		ns
Rise Time	$t_r$				5.3		
Turn-Off Delay Time	$t_{d(OFF)}$				21		
Fall Time	$t_f$				10		
Turn-On Delay Time	$t_{d(ON)}$	P	$V_{GS} = -4.5\text{ V}, V_{DD} = -10\text{ V}, I_D = -430\text{ mA},$ $R_G = 10\ \Omega$		9.2		
Rise Time	$t_r$				6.5		
Turn-Off Delay Time	$t_{d(OFF)}$				29		
Fall Time	$t_f$				19.5		

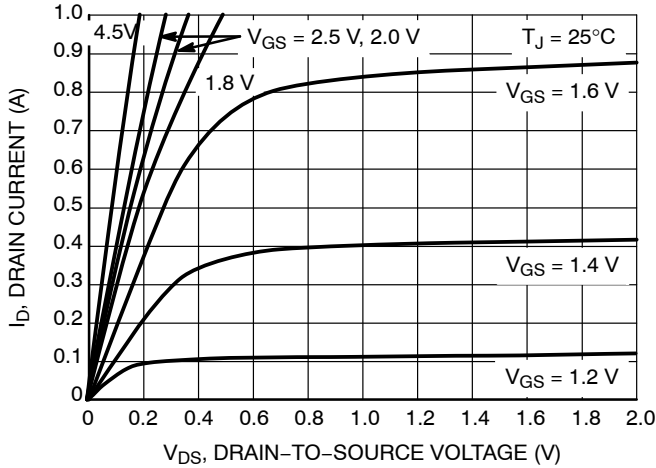
### Drain-Source Diode Characteristics

Forward Diode Voltage	$V_{SD}$	N	$V_{GS} = 0\text{ V}, T_J = 25^\circ\text{C}$	$I_S = 350\text{ mA}$		0.77	1.2	V
		P		$I_S = -350\text{ mA}$		-0.77	-1.2	
		N	$V_{GS} = 0\text{ V}, T_J = 125^\circ\text{C}$	$I_S = 350\text{ mA}$		0.65		
		P		$I_S = -350\text{ mA}$		0.63		
Reverse Recovery Time	$t_{RR}$	N	$V_{GS} = 0\text{ V},$ $dI_S/dt = 100\text{ A}/\mu\text{s}$	$I_S = 350\text{ mA}$		9.4		ns
		P		$I_S = -350\text{ mA}$		14.6		

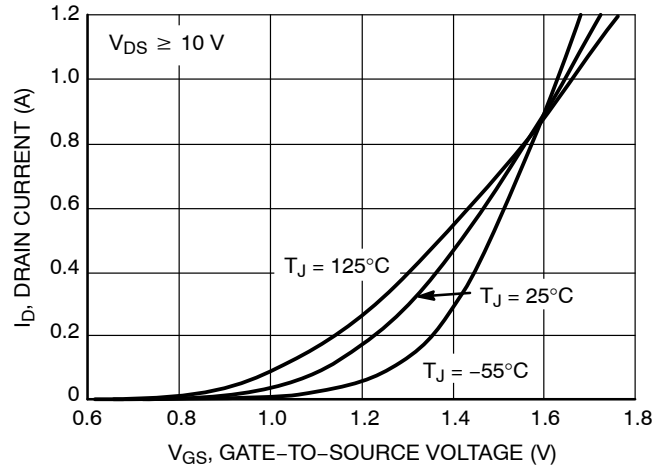
4. Switching characteristics are independent of operating junction temperatures

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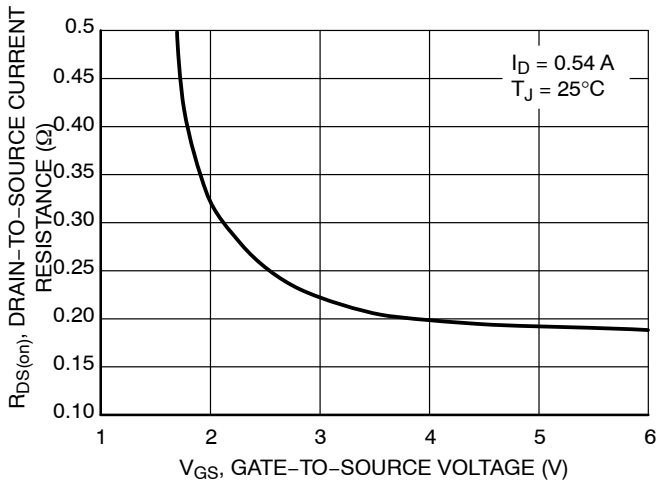
## N-CHANNEL TYPICAL PERFORMANCE CURVES ( $T_J = 25^\circ\text{C}$ unless otherwise noted)



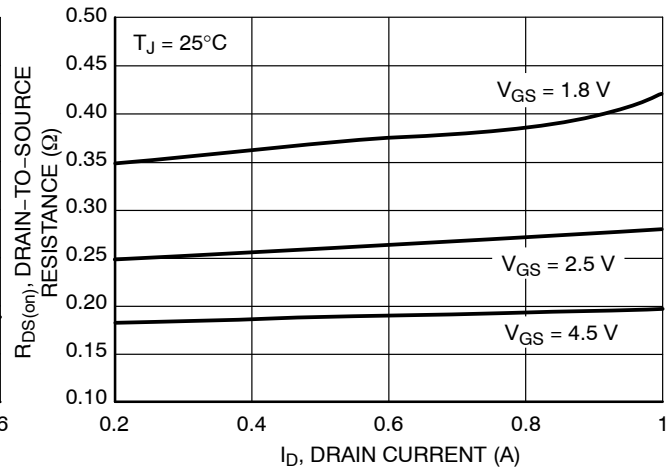
**Figure 1. On-Region Characteristics**



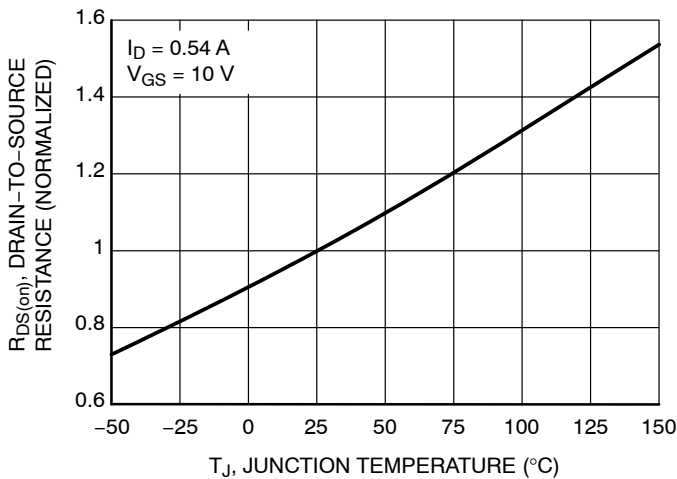
**Figure 2. Transfer Characteristics**



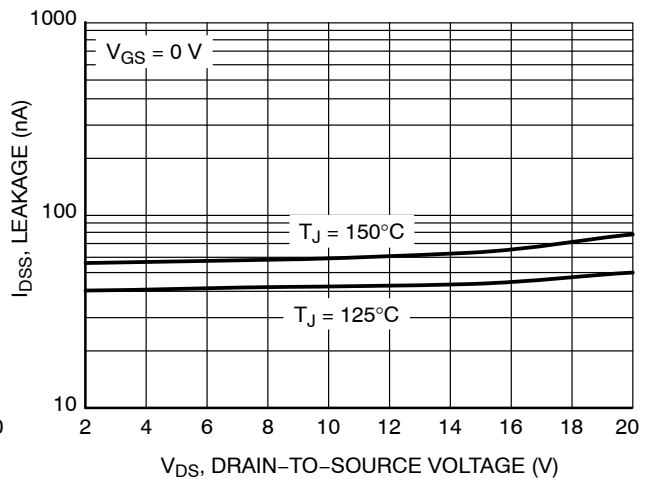
**Figure 3. On-Resistance versus Gate-to-Source Voltage**



**Figure 4. On-Resistance versus Drain Current and Gate Voltage**



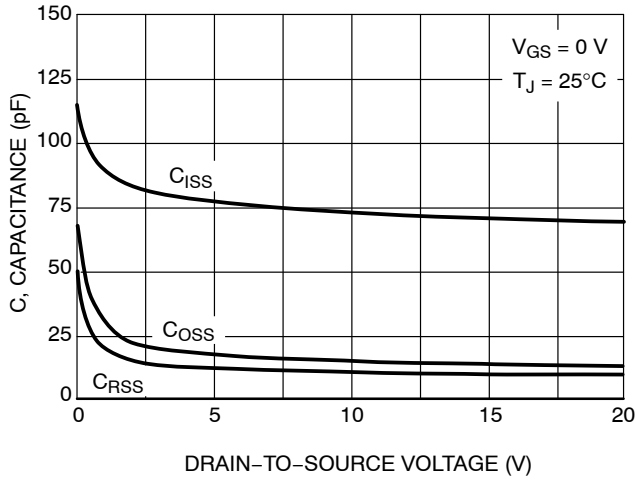
**Figure 5. On-Resistance Variation with Temperature**



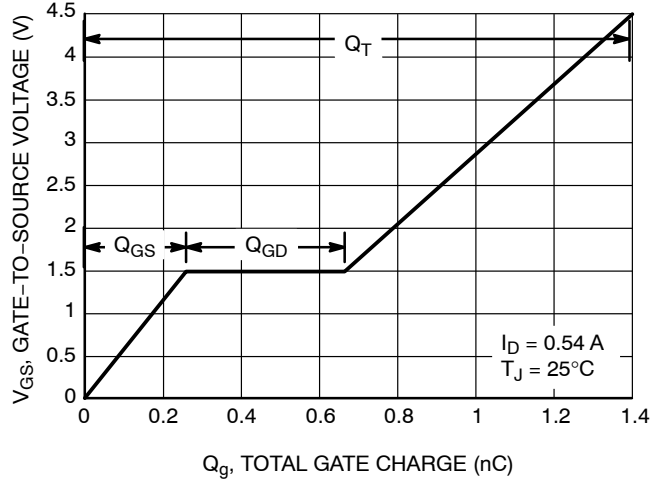
**Figure 6. Drain-to-Source Leakage Current versus Voltage**

# NTZD3156C

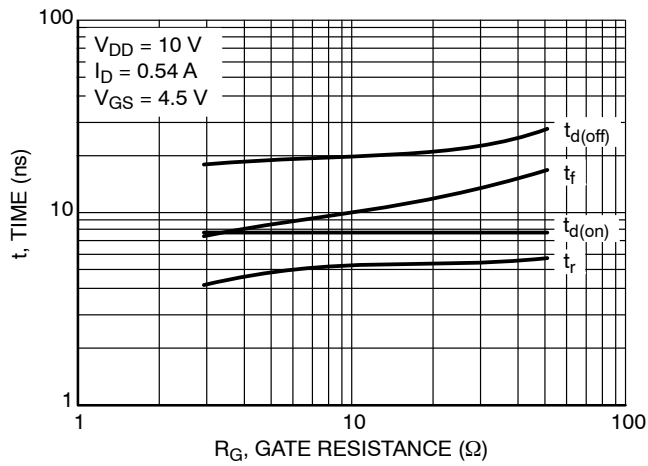
## N-CHANNEL TYPICAL PERFORMANCE CURVES ( $T_J = 25^\circ\text{C}$ unless otherwise noted)



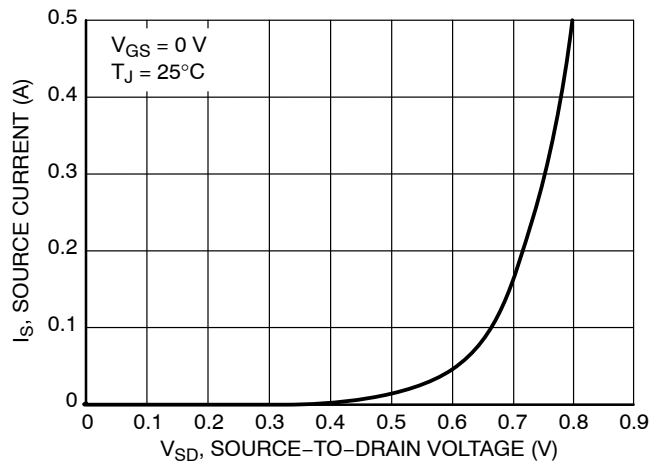
**Figure 7. Capacitance Variation**



**Figure 8. Gate-to-Source and Drain-to-Source Voltage versus Total Charge**



**Figure 9. Resistive Switching Time Variation versus Gate Resistance**



**Figure 10. Diode Forward Voltage versus Current**

P-CHANNEL TYPICAL PERFORMANCE CURVES ( $T_J = 25^\circ\text{C}$  unless otherwise noted)

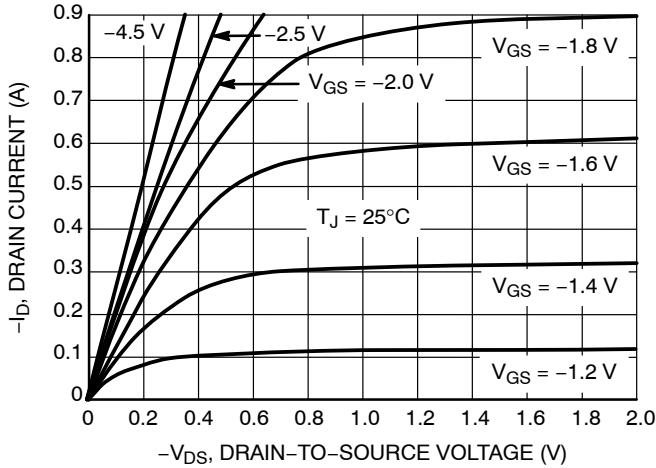


Figure 11. On-Region Characteristics

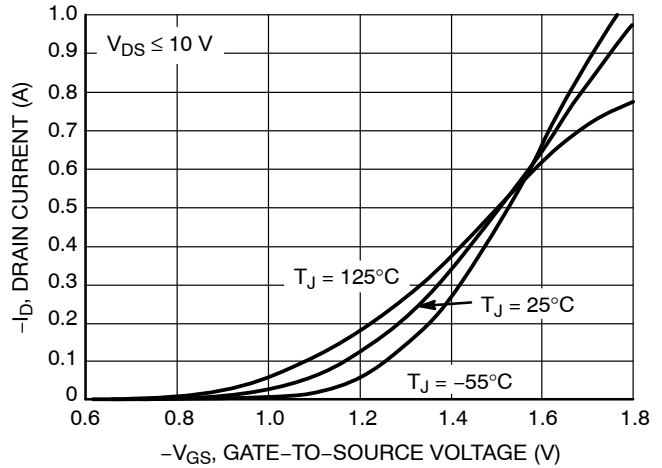


Figure 12. Transfer Characteristics

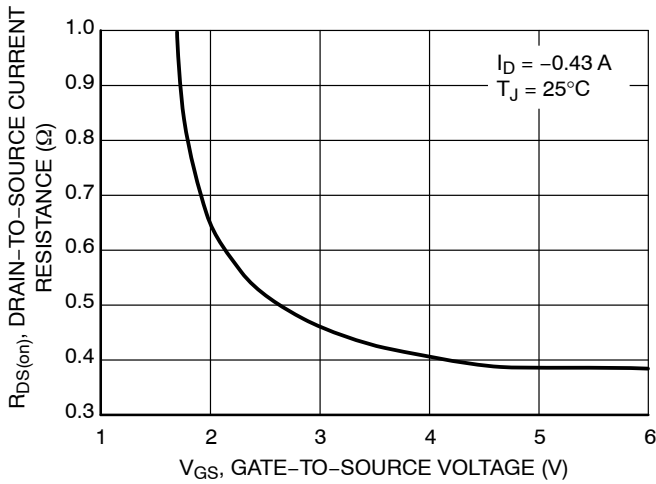


Figure 13. On-Resistance versus Gate-to-Source Voltage

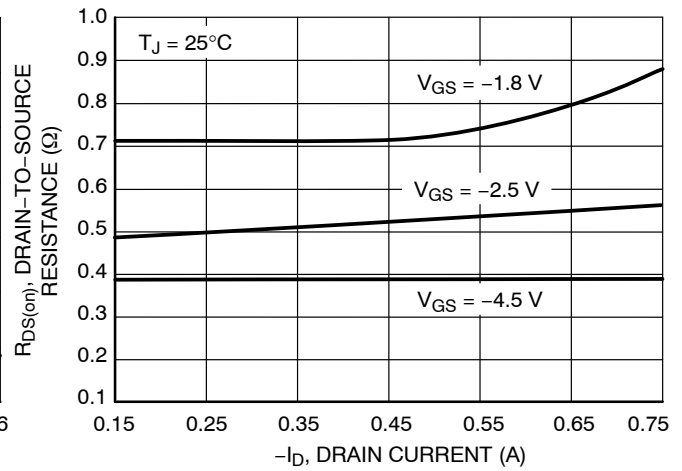


Figure 14. On-Resistance versus Drain Current and Gate Voltage

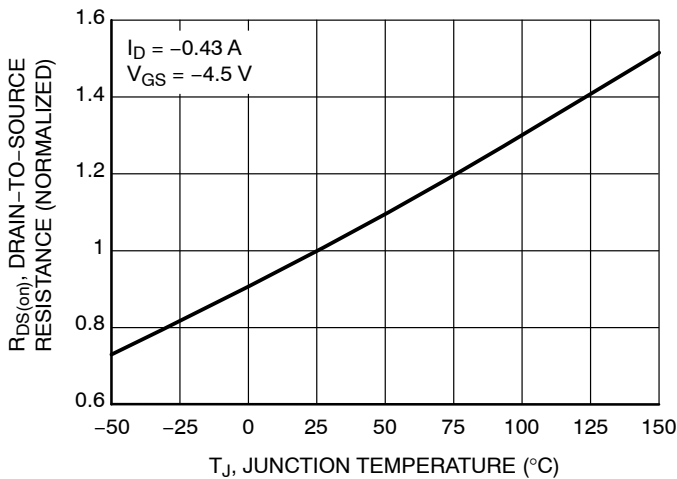


Figure 15. On-Resistance Variation with Temperature

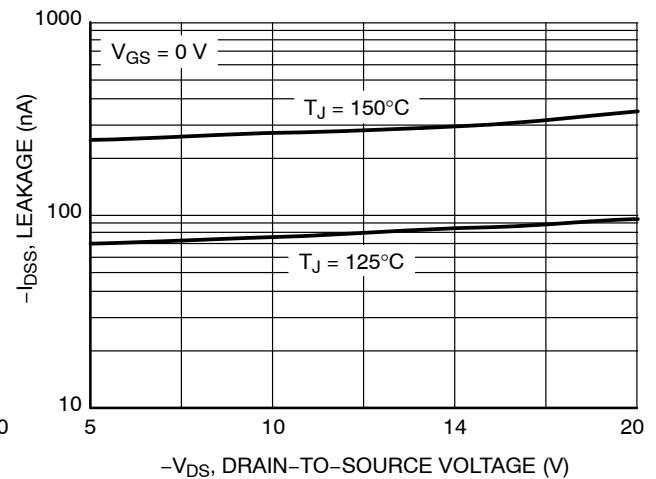


Figure 16. Drain-to-Source Leakage Current versus Voltage

# NTZD3156C

## P-CHANNEL TYPICAL PERFORMANCE CURVES ( $T_J = 25^\circ\text{C}$ unless otherwise noted)

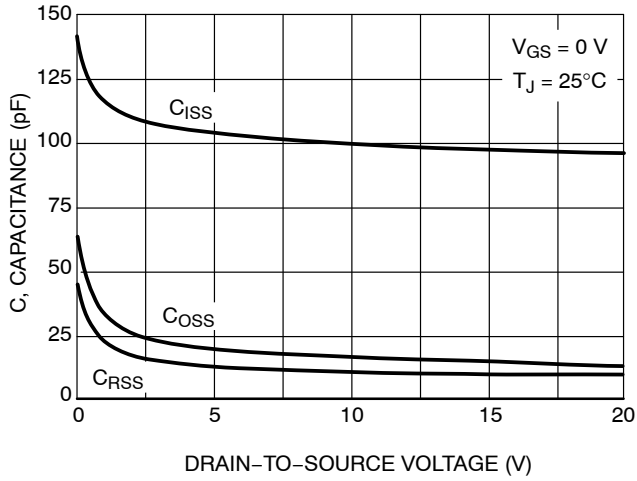


Figure 17. Capacitance Variation

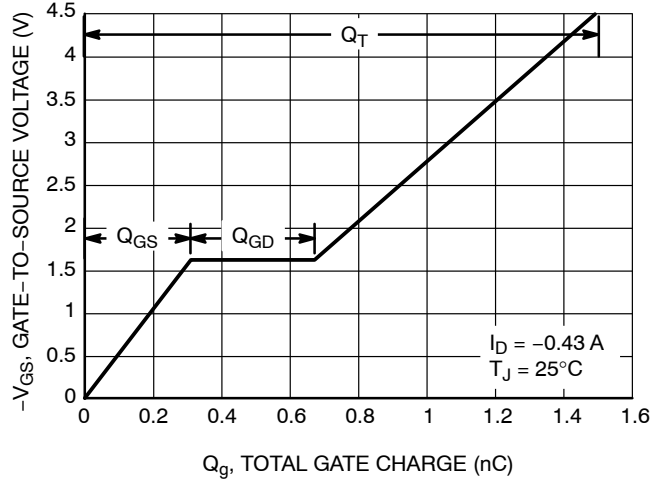


Figure 18. Gate-to-Source and Drain-to-Source Voltage versus Total Charge

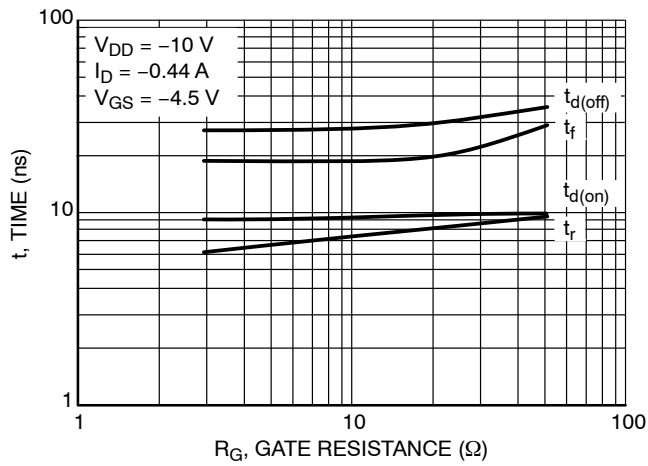


Figure 19. Resistive Switching Time Variation versus Gate Resistance

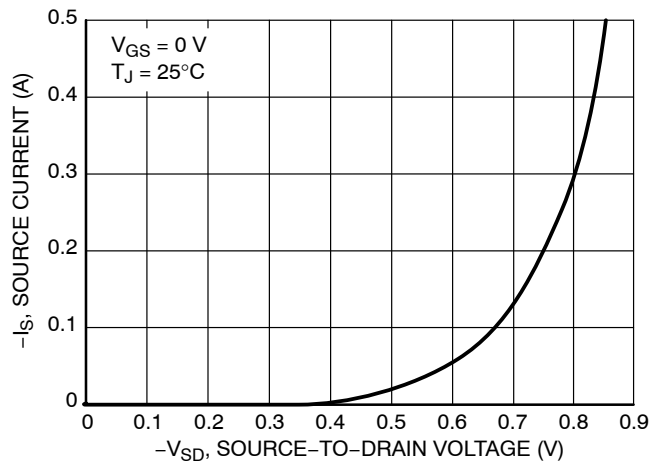
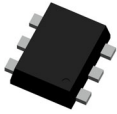


Figure 20. Diode Forward Voltage versus Current

# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

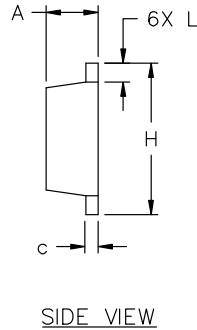
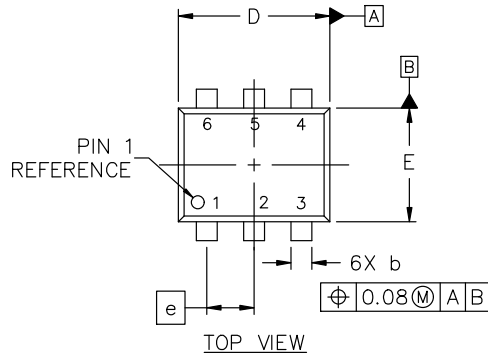


**SOT-563-6 1.60x1.20x0.55, 0.50P**  
**CASE 463A**  
**ISSUE J**

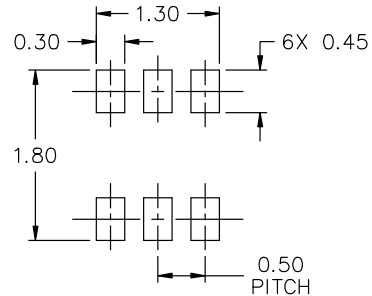
DATE 15 FEB 2024

**NOTES:**

1. DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5-2018.
2. ALL DIMENSION ARE IN MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.



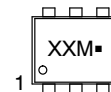
DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.50	0.55	0.60
b	0.17	0.22	0.27
c	0.08	0.13	0.18
D	1.50	1.60	1.70
E	1.10	1.20	1.30
e	0.50 BSC		
H	1.50	1.60	1.70
L	0.10	0.20	0.30



- |  |   |  |
|--|---|--|
| <p><b>STYLE 1:</b><br/>         PIN 1. EMITTER 1<br/>         2. BASE 1<br/>         3. COLLECTOR 2<br/>         4. EMITTER 2<br/>         5. BASE 2<br/>         6. COLLECTOR 1</p> | <p><b>STYLE 2:</b><br/>         PIN 1. EMITTER 1<br/>         2. EMITTER 2<br/>         3. BASE 2<br/>         4. COLLECTOR 2<br/>         5. BASE 1<br/>         6. COLLECTOR 1</p>  | <p><b>STYLE 3:</b><br/>         PIN 1. CATHODE 1<br/>         2. CATHODE 1<br/>         3. ANODE/ANODE 2<br/>         4. CATHODE 2<br/>         5. CATHODE 2<br/>         6. ANODE/ANODE 1</p> |
| <p><b>STYLE 4:</b><br/>         PIN 1. COLLECTOR<br/>         2. COLLECTOR<br/>         3. BASE<br/>         4. EMITTER<br/>         5. COLLECTOR<br/>         6. COLLECTOR</p>      | <p><b>STYLE 5:</b><br/>         PIN 1. CATHODE<br/>         2. CATHODE<br/>         3. ANODE<br/>         4. ANODE<br/>         5. CATHODE<br/>         6. CATHODE</p>                | <p><b>STYLE 6:</b><br/>         PIN 1. CATHODE<br/>         2. ANODE<br/>         3. CATHODE<br/>         4. CATHODE<br/>         5. CATHODE<br/>         6. CATHODE</p>                       |
| <p><b>STYLE 7:</b><br/>         PIN 1. CATHODE<br/>         2. ANODE<br/>         3. CATHODE<br/>         4. CATHODE<br/>         5. ANODE<br/>         6. CATHODE</p>               | <p><b>STYLE 8:</b><br/>         PIN 1. DRAIN<br/>         2. DRAIN<br/>         3. GATE<br/>         4. SOURCE<br/>         5. DRAIN<br/>         6. DRAIN</p>                        | <p><b>STYLE 9:</b><br/>         PIN 1. SOURCE 1<br/>         2. GATE 1<br/>         3. DRAIN 2<br/>         4. SOURCE 2<br/>         5. GATE 2<br/>         6. DRAIN 1</p>                     |
| <p><b>STYLE 10:</b><br/>         PIN 1. CATHODE 1<br/>         2. N/C<br/>         3. CATHODE 2<br/>         4. ANODE 2<br/>         5. N/C<br/>         6. ANODE 1</p>              | <p><b>STYLE 11:</b><br/>         PIN 1. EMITTER 2<br/>         2. BASE 2<br/>         3. COLLECTOR 1<br/>         4. EMITTER 1<br/>         5. BASE 1<br/>         6. COLLECTOR 2</p> |  |

\* FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

**GENERIC MARKING DIAGRAM\***



- XX = Specific Device Code
- M = Month Code
- = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

<b>DOCUMENT NUMBER:</b>	<b>98AON11126D</b>	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
<b>DESCRIPTION:</b>	<b>SOT-563-6 1.60x1.20x0.55, 0.50P</b>	<b>PAGE 1 OF 1</b>

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